

Final Product/Process Change Notification Document #:FPCN25729XQ Issue Date:09 May 2025

Title of Change:	Wafer Fab Site Addition products.	Wafer Fab Site Addition of onsemi, Bucheon Korea as alternate fab site for ESD and Surge Protection products.		
Proposed First Ship date:	29 Aug 2025 or earlier	29 Aug 2025 or earlier if approved by customer		
Contact Information:	Contact your local onse	Contact your local onsemi Sales Office.		
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
Additional Reliability Data:	Contact your local onse	Contact your local onsemi Sales Office.		
Type of Notification:	days prior to implemer onsemi will consider th	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com		
Marking of Parts/ Traceability of Change:	Changed material can b	Changed material can be identified by lot code		
Change Category:	Wafer Fab Change	Wafer Fab Change		
Change Sub-Category(s):	Manufacturing Site Add	Manufacturing Site Addition		
Sites Affected:				
onsemi Sites		External Foundry/Subcon Sites		
onsemi Bucheon, Korea		None		
fab site for ESD and Surge Protection prod	ucts.	the qualification of onsemi Bucheon, Korea Wafer Fab as an additional wafer		
Upon expiration of this FPCN, affected par	ts can be sourced from eithe	r onsemi Bucheon, Korea or LA Semiconductor wafer fab.		

There are no product marking changes as a result of this change.

	Before Change Description	After Change Description	
Manufacturing location for Wafer Fab	LA Semiconductor, Idaho, United States	onsemi Bucheon, Korea, LA Semiconductor, Idaho, United States	
		LA Semiconductor, Idaho, United Stat	

onsemi

Final Product/Process Change Notification Document #:FPCN25729XQ Issue Date:09 May 2025

Reliability Data Summary:

QV DEVICE NAME: ESD7321MUT5G RMS: S94408 PACKAGE: X3DFN

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1@260°C		0/693
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle	
ESD7481MUT5G	ESD7321MUT5G	
ESD7382MUT5G	ESD7321MUT5G	
ESD7381MUT5G	ESD7321MUT5G	